

280 Watts - 60 Volts, 300 μs, 10% L-Band Radar 1200 - 1400 MHz

GENERAL DESCRIPTION

The 1214GN-280 is an internally matched, COMMON SOURCE, class AB, GaN on SiC HEMT transistor capable of providing over 17dB gain, 280 Watts of pulsed RF output power at 300µs pulse width, 10% duty factor across the 1200 to 1400 MHz band.

Market Application – 1214GN-280 is designed for L-Band Pulsed Radar

ABSOLUTE MAXIMUM RATINGS

Maximum Power Dissipation

Device Dissipation @ 25°C 600 W

Maximum Voltage and Current

Drain-Source Voltage (V_{DSS}) 150 V Gate-Source Voltage (V_{GS}) -8 to +0 V

Maximum Temperatures

Storage Temperature (T_{STG}) -55 to +125° C Operating Junction Temperature +250 °C

CASE OUTLINE 55-KR Common Source



ELECTRICAL CHARACTERISTICS @ 25°C

Symbol	Characteristics	Test Conditions	Min	Тур	Max	Units
Pout	Output Power	Pout=280W, Freq=1200,1300,1400 MHz	280	300		W
Gp	Power Gain	Pout=280W, Freq=1200,1300,1400 MHz	17	17.3		dB
ηd	Drain Efficiency	Pout=280W, Freq=1200,1300,1400 MHz	47	55		%
Dr	Droop	Pout=280W, Freq=1200,1300,1400 MHz			1.0	dB
VSWR-T	Load Mismatch	Pout=280W, Freq= 1300MHz			3:1	
	Tolerance					
Өјс	Thermal Resistance	Pulse Width=300uS, Duty=10%			0.3	°C/W

• Bias Condition: Vdd=+60V, Idq=50mA average current (Vgs= -2.0 ~ -4.5V typical)

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FUNCTIONAL CHARACTERISTICS @ 25°C

$I_{D(Off)}$	Drain leakage current	$V_{gS} = -8V, V_D = 60V$		10	mA
$I_{G(Off)}$	Gate leakage current	$V_{gS} = -8V$, $V_D = 0V$		8	mA
BV _{DSS}	Drain-source breakdown voltage	$V_{gs} = -8V, I_D = 10mA$	250		V

Jan 2013

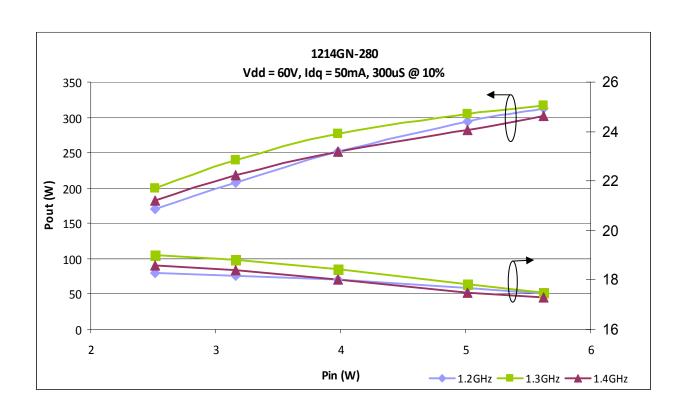
Export Classification: EAR-99



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TYPICAL BROAD BAND PERFORMACE DATA

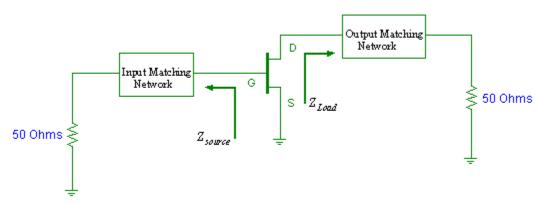
Frequency	Pin (W)	Pout (W)	ld (A)	RL (dB)	Nd (%)	G (dB)	Droop (dB)
1200 MHz	5.6	312	1.0	-9	53	17.45	0.5
1300 MHz	5.6	316	.96	-15	57	17.5	0.3
1400 MHz	5.6	302	.9	-17	58	17.2	0.2





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TRANSISTOR IMPEDANCE INFORMATION



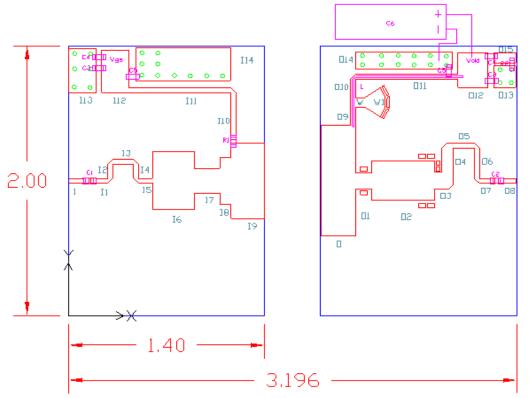
Note: Z_{source} is looking into the input circuit; Z_{Load} is looking into the output circuit.

	Impedance Data				
Freq (GHz)	Zs	ZI			
1.2	2.29 – j2.52	3.18 – j2.32			
1.3	2.32 – j1.47	3.61 – j1.43			
1.4	2.44 – j.40	4.29 – j.56			



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TEST CIRCUIT DIAGRAM



Board Material: Roger Duriod 6006 @ 25 Mil Thickness, Er=6.15

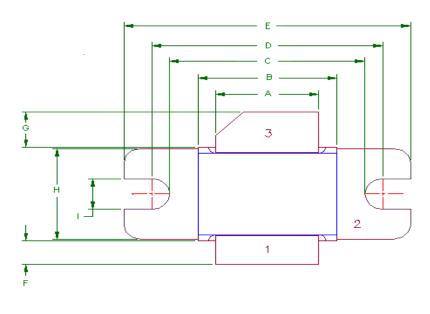


12	140	N.	280	Rev

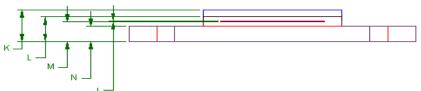
	Compone	ent List		Input P	hysical Circ	uit Lavout	Output	Physical Ci	cuit Lavou
ltem	Description	CIRC Eloc	Value	Item	W (mil)	L (mil)	Item	W (mil)	L (mil)
C1	Chip Cap A size	ATC800A1010JT250XT	100pF	I	35	100	0	820	250
C2	Chip Cap A size	ATC800A680JT250XT	68pF	I1	35	120	01	116	110
C3	Chip Cap B size	ATC200B103KW50XT	10,000pF	12	35	106	02	290	450
C4	Chip Cap B size	ATC100B102102KW50XT	1000pF	13	35	150	03	125	135
C5	Chip Cap B size	ATC100B101FW1000XT	100pF	14	35	106	04	86	170
C6	Electrolytic Cap (63V)	ANY	4700uF	15	35	100	05	35	150
R1	Chip Resistor size 0805	ANY	20.5 ohms	16	430	300	06	35	226
R2	Chip Resistor size 0805	ANY	2 ohm	17	180	182	07	35	110
L	RF Choke 20 AWG Copper wire	е		18	346	78	08	35	125
	L=1350 mil solder on top of the	output choke		19	560	236	09	35	138
	·			110	35	355	010	35	138
Note:				l11	35	745	011	35	730
	Need 2x of C3,C4,C5			112	315	200	012	250	200
				l13	280	190	013	160	140
				114	200	670	014	130	680
							015	70	140
							W	70	60
							1 4 14	100	

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55-KR PACKAGE DIMENSION







1	=	Gate
2	=	Source
3	=	Drain

Dimension Min (mil) Min (mm) Max (mil) Max (mm)





Α	370	9.40	372	9.44
В	498	12.65	500	12.7
С	700	17.78	702	17.83
D	830	21.08	832	21.13
E	1030	26.16	1032	26.21
F	101	2.56	102	2.59
G	151	3.84	152	3.86
Н	385	9.78	387	9.83
I	130	3.30	132	3.35
J	003	.076	004	0.10
K	135	3.43	137	3.48
L	105	2.67	107	2.72

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M	085	2.16	86	2.18
N	065	1.65	66	1.68



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Revision History

Revision Level / Date	Para. Affected	Description
0.1 / 18 January 2013	1	Initial Preliminary Release